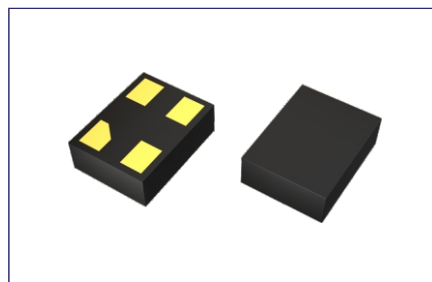


## SMD 2.0X1.5X0.6 CSP PACKAGE

### PRODUCT FEATURES

- Ultra Small size 2.0x1.5x0.6mm
- CSP process with chip scale package
- Standardization of small size
- Good stability and high reliability
- Mainly used in GPS navigation
- TDD/FDD communication and artificial intelligence chips
- ROHS compliant

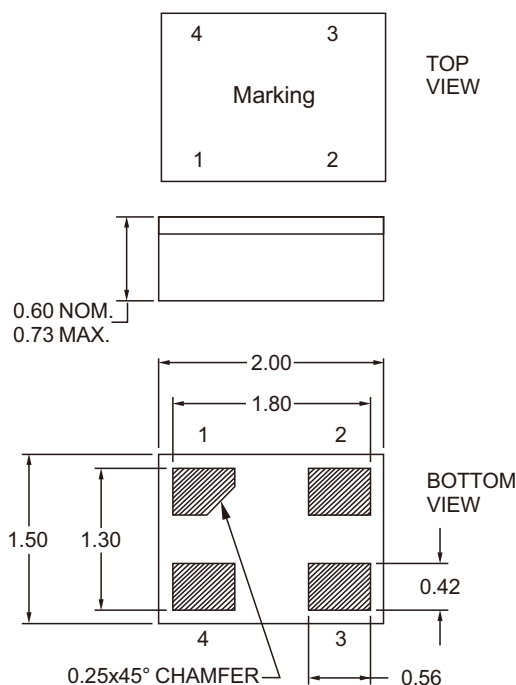
### PRODUCT PHOTO



### PRODUCT SPECIFICATIONS

| Item                        |       | Specifications                | Unit |
|-----------------------------|-------|-------------------------------|------|
| Frequency Range             | $f_c$ | 800~3600MHz                   | MHz  |
| Standard Frequency          |       | 1575.42, 1582.4, 1568, 2655   | MHz  |
| Useful Band Width           |       | 3, 25, 48 or specify          | MHz  |
| Insertion Loss (min)        | IL    | 0.9, 1.3, 1.8, 2.2 or specify | dB   |
| VSWR(max)                   |       | 2.0                           | dB   |
| Operating Temperature Range |       | -40~+85                       | °C   |
| Storage Temperature Range   |       | -40~+85                       | °C   |

### PACKAGE OUTLINE / DIMENSIONS



| Pin No. | Description |
|---------|-------------|
| 1       | Input       |
| 3       | Output      |
| 2,4     | Case Ground |